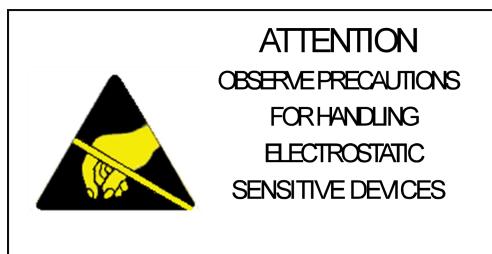


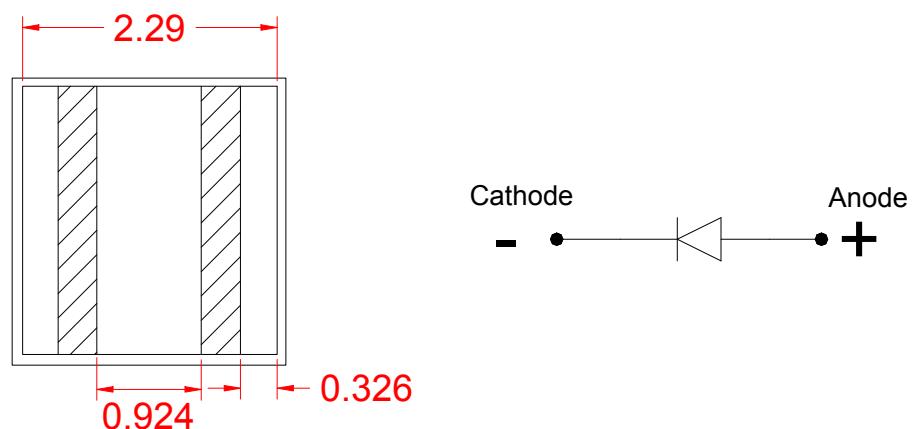
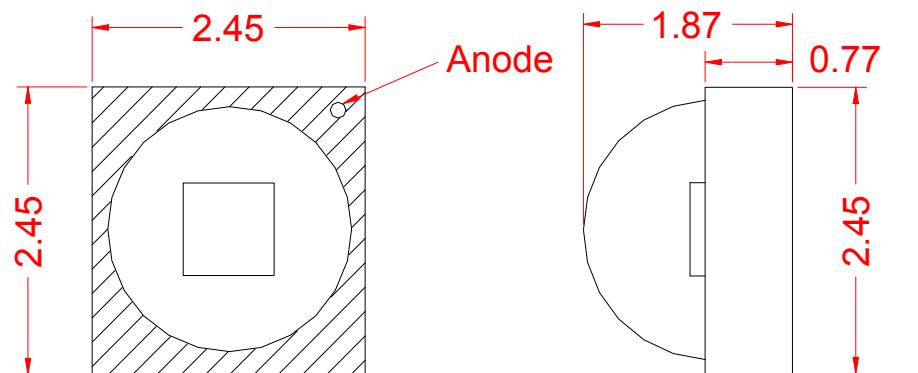
WCN-2525NW-120-CE-40**SPECIFICATION**

| WCN | | | CUSTOMER Confirmed |
|---------------------|------------------------|---|-----------------------|
| Prepared by | Checked by | Approved by | |
| LiuGuo 2018-11-9 | ZhangChun 2018-11-9 |  | |



Description

- ◆ Viewing angle:120 deg
- ◆ The materials of the LED dice is InGaN
- ◆ 2.45mm×2.45mm×1.87mm
- ◆ RoHS compliant lead-free soldering compatible

Package Outline**NOTES:**

1. All dimensions units are millimeters ;
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

Absolute Maximum Ratings at Ta=25°C

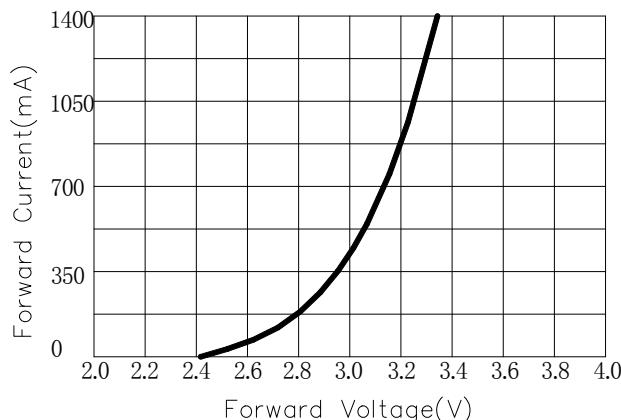
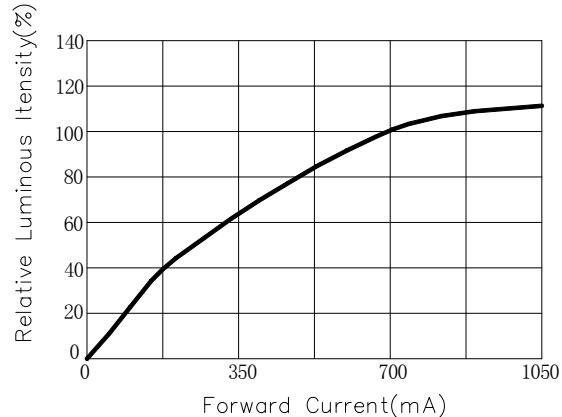
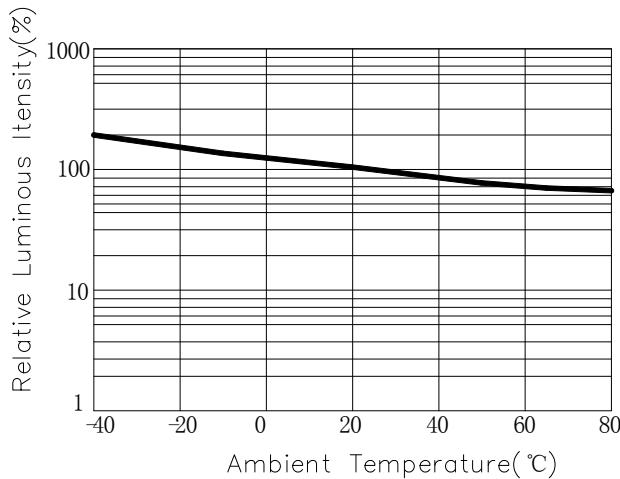
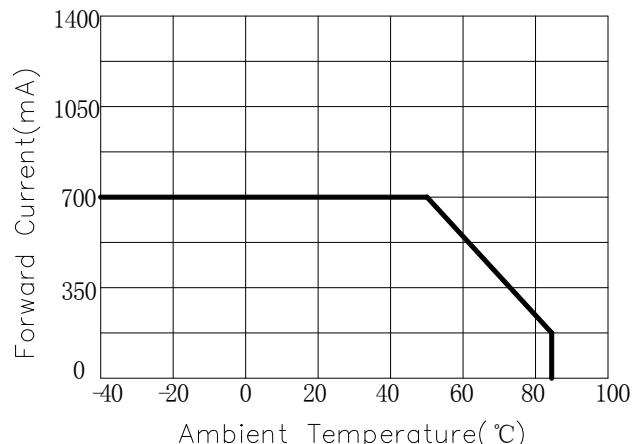
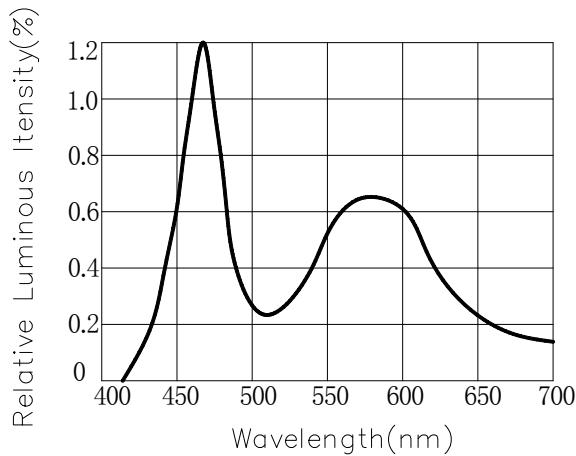
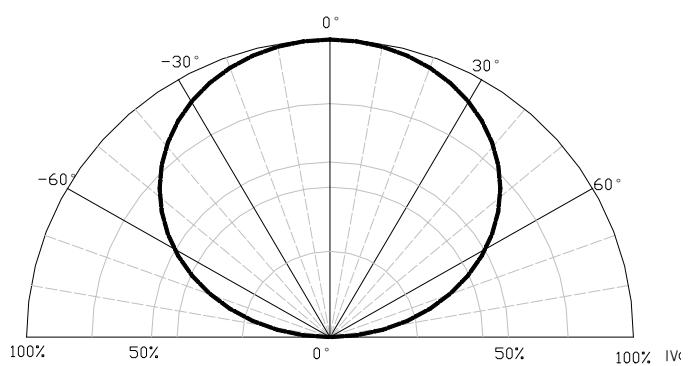
| Parameter | Symbol | Rating | Units |
|-------------------------|--------|-----------|-------|
| Power Dissipation | Pd | 2380 | mW |
| Forward current | If | 700 | mA |
| Peak Forward Current | IPF | 1000 | mA |
| Electrostatic Discharge | ESD | 1000 | V |
| Operating temperature | Topr | -30~+85 | °C |
| Storage temperature | Tstg | -40 ~+100 | °C |
| junction temperature | Tj | 95 | °C |

Electrical/Optical characteristics at Ta=25°C

| Item | test condition | Symbol | Value | | | Unit |
|------------------------------|----------------|----------|-------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Forward voltage | If=700mA | Vf | 2.8 | -- | 3.0 | V |
| | | | 3.0 | -- | 3.2 | V |
| | | | 3.2 | -- | 3.4 | V |
| Luminous intensity | If=700mA | Iv | 160 | -- | 180 | lm |
| | | | 180 | -- | 200 | lm |
| | | | 200 | -- | 220 | lm |
| Correlated Color Temperature | If=700mA | CCT | 4000 | -- | 4500 | k |
| Viewing angle at 50% Iv | If=700mA | 2θ1/2 | -- | 120 | -- | Deg |
| Thermal resistance | If=700mA | Rth(j-s) | -- | -- | 450 | °C/W |

NOTE:

1. 1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is 0.1V.
3. the above luminous intensity measurement allowance tolerance ±10%.

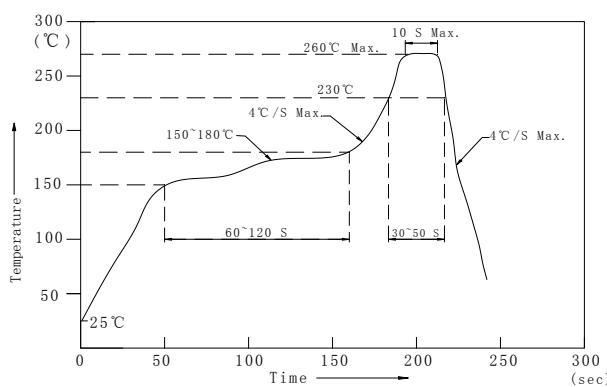
Optical characteristics curves**Forward Current VS Forward Voltage****Relative Flux VS Forward Current****Relative Flux VS Ambient Temperature****Forward Current VS Ambient Temperature****Relative Spectral Distribution****Typical Spectral Distribution**

Test items and results of reliability

| Type | Test Item | Test Conditions | Note | Number of Damaged |
|------------------------|------------------------------|------------------------------------|-----------|-------------------|
| Environmental Sequence | Reflow | T _a =260°C max T=10s | 2 times | 0/22 |
| | Temperature Cycle | -40°C 30min ↑ 100°C 30min | 100 cycle | 0/22 |
| | Thermal Shock | -40°C 15min ↑ 100°C 15min | 100 cycle | 0/22 |
| | High Humidity Heat Cycle | 30°C ⇄ 65°C 90%RH 24hrs/1cycle | 10 cycle | 0/22 |
| | High Temperature Storage | T _a =100°C | 1000 hrs | 0/22 |
| | Low Temperature Storage | T _a =-40°C | 1000 hrs | 0/22 |
| | Humidity Heat Storage | T _a =60°C RH=90% | 1000 hrs | 0/22 |
| | Low Temperature Storage | T _a =-30°C | 1000 hrs | 0/22 |
| Operation Sequence | Life Test | T _a =25°C IF=20mA | 1000 hrs | 0/22 |
| | High Humidity Heat Life Test | 60°C RH=90% IF=10mA | 500 hrs | 0/22 |
| | Low Temperature Life Test | T _a =-20°C IF=20mA | 1000 hrs | 0/22 |

Reflow Profile

■ Reflow Temp/Time



Notes:

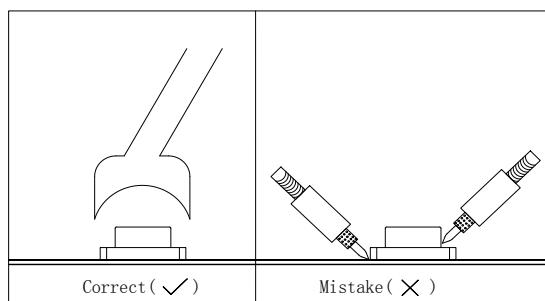
1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■ Soldering iron

Basic spec is $\leq 5\text{ sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{ sec}$). Power dissipation of iron should be smaller than 20W , and temperatures should be controllable .Surface temperature of the device should be under 230°C .

■ Rework

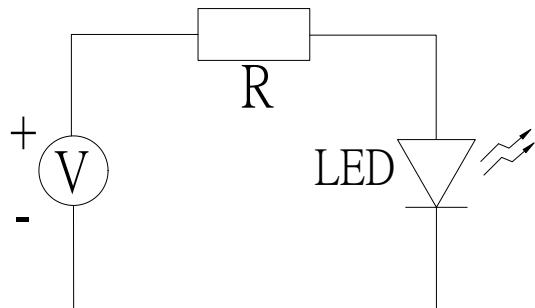
1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C~30°C(41°F~86°F)

2.2 Shelf life in sealed bag: 12 month at <5°C~30°C and <30% R.H. After the package is

Opened, the products should be used within a week or they should be keeping to stored at ≤ 20 R.H. with zip-lock sealed.

3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as

followings:

3.1 $70\pm3^\circ\text{C}$ x(12~24hrs) and <5%RH, taped reel type

3.2 $100\pm3^\circ\text{C}$ x(45min~1hr), bulk type

3.3 $130\pm3^\circ\text{C}$ x(15~30min), bulk type